

Please delete the present Abstract of the Disclosure.

Please add the following new Abstract of the Disclosure:

An electroplating process of electroplating an electrically conductive substrate is described. The process includes electroplating intermittently to a predetermined plating thickness using the substrate surface as a cathode and a plating metal as an anode at a constant voltage between the anode and the cathode by repeating application of a voltage between a cathode and an anode and interruption of the application alternately. It is described that a voltage time/interruption time ratio is 0.1 to 1.0, a voltage time is not longer than 10 seconds, and an interruption time is not less than 1×10^{-12} seconds.